

CY62167GN30-45BVXIT

Status: In Production



CY62167GN30-45BVXIT	
Automotive Qualified	N
Density (Kb)	16384
Frequency (MHz)	N/A
Max. Operating Temp. (°C)	85
Max. Operating VCCQ (V)	3.60
Max. Operating Voltage (V)	3.60
Min. Operating Temp. (°C)	-40
Min. Operating VCCQ (V)	2.20
Min. Operating Voltage (V)	2.20
Organization (X x Y)	1M x 16
Speed (ns)	45
Temp. Classification	Industrial

PACKAGING/ORDERING	
Package	BGA
No. of Pins	48
Package Dimensions	314 L x 1 H x 236 W (Mils)
Package Weight	79.26 (mgs)
Package Cross Section Drawing	Download
Package Carrier	REEL
Package Carrier Drawing / Orientation	Reel Drawing , Tape Drawing , Package Orientation
Standard Pack Quantity	2000
Minimum Order Quantity (MOQ)	2000
Order Increment	2000
Estimated Lead Time (days)	42
HTS Code	8542.32.0040
ECCN	(B.2.B.)
ECCN Suball	3A991

QUALITY AND ROHS	
Moisture Sensitivity Level (MSL)	3
Peak Reflow Temp. (°C)	260 (Cypress Reflow Profile)
RoHS Compliant	Y Print RoHS Certificate of Compliance
PB Free	Y
Lead/Ball Finish	Sn/Ag/Cu
Marking	Cypress Marking Format
Package Material Declaration	
48 - BGA (6X8MM) PB-FREE PACKAGE MATERIAL DECLARATION DATASHEET <i>Last Update: Nov 12, 2015</i>	
IPC 1752 Material Declaration	
IPC-1752-2_V1.1_BGA 48 (6 X 8 MM) _ASET_SNAGCU(SAC105) <i>Last Update: Jun 19, 2014</i>	
IPC-1752-2_V1.1_BGA 48 (6 X 8 MM) _CML_SNAGCU <i>Last Update: Jun 19, 2014</i>	
RoHS Analysis Certificates (CoA)	
ROHS ANALYSIS REPORT BGA (BK48A,BK48B,BK48C,BZ36,BZ48A,BZ48B,BZ54C,BZ56,BZ100) USING MOLD COMPOUND KEG2270, ADHESIVE QMI506, SAC105 - CML ASSEMBLY <i>Last Update: Jul 04, 2012</i>	
PACKAGE ROHS ANALYSIS REPORT - BGA (BZ 36,48,52,56,100) USING MOLD COMPOUND KE-G2270, ADHESIVE 2025D, SAC105 - ASE TAIWAN ASSEMBLY <i>Last Update: Jul 04, 2012</i>	

TECHNICAL DOCUMENTS
Application Notes (2)
AN88889 - Mitigating Single-Event Upsets Using Cypress's 65-nm Asynchronous SRAM Oct 05, 2015
AN89371 - Power Saving With Cypress's 65-nm Asynchronous PowerSnooze™ SRAM Aug 26, 2015